COMPLIANT

**HALOGEN** 



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# SMD Photovoltaic Solar Cell Protection Schottky Rectifier



PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	12 A		
V <sub>RRM</sub>	40 V		
I <sub>FSM</sub>	280 A		
E <sub>AS</sub>	20 mJ		
V <sub>F</sub> at I <sub>F</sub> = 12 A	0.43 V		
T <sub>J</sub> max.	150 °C		

#### **TYPICAL APPLICATIONS**

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

#### **FEATURES**

- Very low profile typical height of 1.1 mm
- · Ideal for automated placement
- · Guardring for overvoltage protection
- Low forward voltage drop, low power losses
- · High efficiency
- · Low thermal resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- · Not recommended for PCB bottom side wave mounting
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

#### **MECHANICAL DATA**

Case: TO-277A (SMPC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	SS12P4S	UNIT	
Device marking code		124S		
Maximum repetitive peak reverse voltage	$V_{RRM}$	40	V	
Maximum DC forward current (fig. 1)	I <sub>F</sub>	12 <sup>(1)</sup> 4.4 <sup>(2)</sup>	А	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	280	А	
Non-repetitive avalanche energy at I <sub>AS</sub> = 2 A, T <sub>J</sub> = 25 °C	E <sub>AS</sub>	20	mJ	
Operating junction and storage temperature range	T <sub>OP,</sub> T <sub>STG</sub>	- 55 to + 150	°C	
Junction temperature in DC forward current without reverse bias, t $\leq$ 1 h $^{(3)}$	T <sub>J</sub>	≤ 200	°C	

(1) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink

<sup>(2)</sup> Free air, mounted on recommended copper pad area

<sup>(3)</sup> Meets the requirements of IEC 61215 Ed. 2 bypass diode thermal test

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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
landardan aya farrayda albana (1)	$I_F = 6 \text{ A}$ $I_F = 12 \text{ A}$ $T_A = 25 \text{ °C}$	V-	0.43 0.50	- 0.60	V	
Instantaneous forward voltage (1)	I <sub>F</sub> = 6 A I <sub>F</sub> = 12 A	T <sub>A</sub> = 125 °C	V <sub>F</sub>	0.33 0.43	- 0.52	
Reverse current (2)	V <sub>R</sub> = 40 V	T <sub>A</sub> = 25 °C T <sub>A</sub> = 125 °C	I <sub>R</sub>	100 50	800 100	μA mA
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	750	-	pF

#### Notes

 $^{(1)}$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

 $^{(2)}$  Pulse test: Pulse width  $\leq$  40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL SS12P4S		UNIT	
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)</sup> R <sub>θJM</sub> <sup>(2)</sup>	100 3	°C/W	

#### **Notes**

 $^{(1)}$  Free air, mounted on recommended copper pad area. Thermal resistance  $R_{\theta JA}$  - junction to ambient.

<sup>(2)</sup> Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance R<sub>B,IM</sub> - junction to mount.

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
SS12P4S-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel	
SS12P4S-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel	

### **RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25 °C unless otherwise noted)

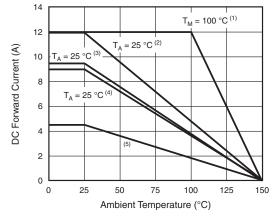


Figure 1. Maximum Current Derating Curve

### Notes

- $^{(1)}$  Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink,  $T_{\rm M}$  measured at the terminal of cathode hand
- $^{(2)}$  Mounted on 30 mm x 30 mm Al PCB (R $_{\theta JA}$  = 20 °C/W)
- $^{(3)}$  Mounted on 30 mm x 30 mm x 2 copper pad areas FR4 PCB ( $R_{\theta JA} = 30$  °C/W)
- $^{(4)}$  Mounted on 25 mm x 25 mm x 2 copper pad areas FR4 PCB  $(R_{\theta,J}=30~^{\circ}\text{C/W})$
- <sup>(5)</sup> Free air, mounted on recommended copper pad area  $(R_{\theta JA} = 100 \, ^{\circ}C/W)$



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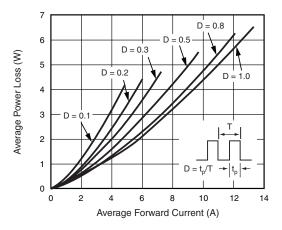


Figure 2. Forward Power Loss Characteristics

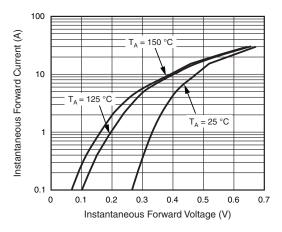


Figure 3. Typical Instantaneous Forward Characteristics

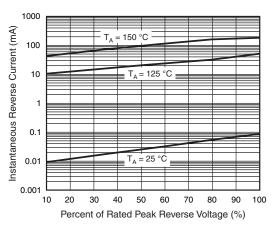


Figure 4. Typical Reverse Leakage Characteristics

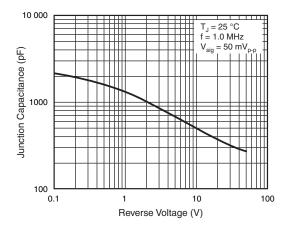
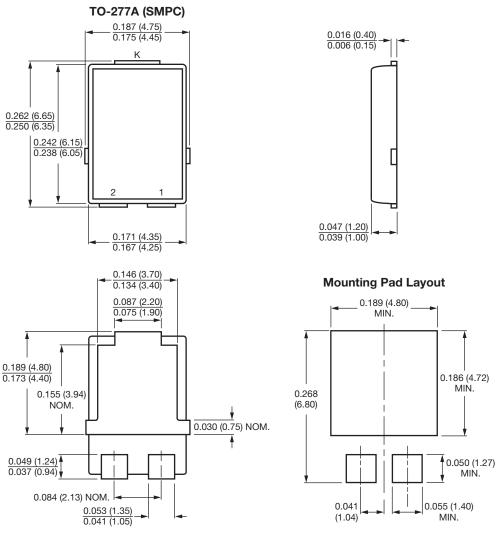


Figure 5. Typical Junction Capacitance

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### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



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